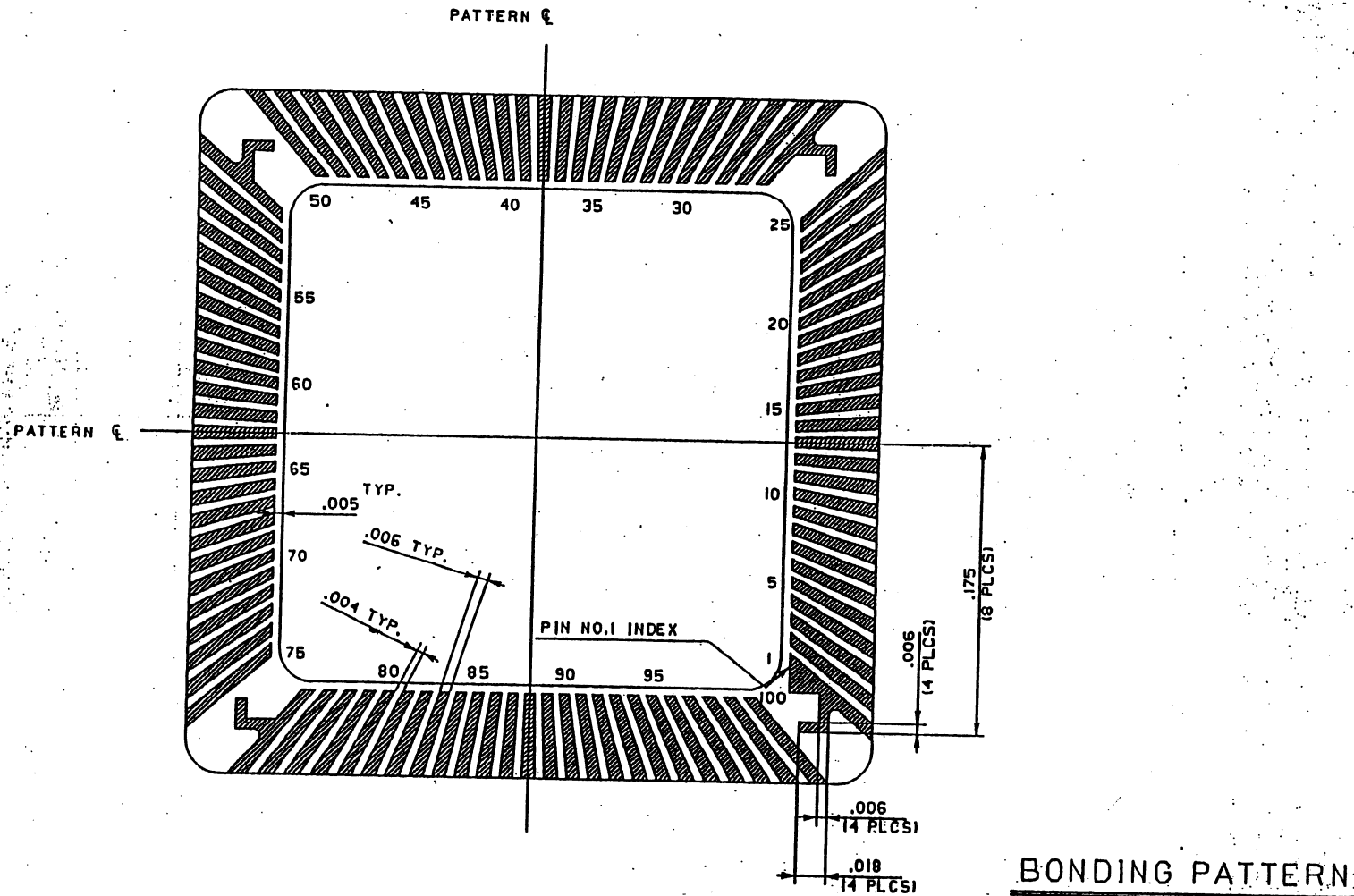


- NOTES
- 1 ALL EXPOSED METAL AND METALLIZED AREAS SHALL BE GOLD PLATED 88 MICRO-INCHES MIN. THICKNESS OVER NICKEL PLATED.
 - 2 SEAL AREA TO BE METALLIZED.
 - 3 DIE ATTACH AREA TO BE METALLIZED.
 - 4 SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 - 5 LEAD RESISTANCE :
B/F NO.1,2,3,26,37,39,51,62,63,76,87,88.....0.30 MAX.
THE OTHERS.....0.50 MAX.



SSM P/N CPG10020

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SSM P/N CPG10020

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	B2	21	K2	41	M8	61	H13	81	A10
2	B1	22	L1	42	L8	62	G12	82	B9
3	C2	23	M1	43	N9	63	G11	83	A9
4	C1	24	L2	44	M9	64	G13	84	C8
5	D2	25	N1	45	N10	65	F13	85	B8
6	D1	26	M2	46	M10	66	F12	86	A8
7	E2	27	N2	47	N11	67	F11	87	B7
8	E1	28	M3	48	N12	68	E13	88	C7
9	F3	29	N3	49	M11	69	E12	89	A7
10	F2	30	M4	50	N13	70	D13	90	A6
11	F1	31	N4	51	M12	71	D12	91	B6
12	G2	32	M5	52	M13	72	C13	92	C6
13	G3	33	N5	53	L12	73	B13	93	A5
14	G1	34	L6	54	L13	74	C12	94	B5
15	H1	35	M6	55	K12	75	A13	95	A4
16	H2	36	N6	56	K13	76	B12	96	B4
17	H3	37	M7	57	J12	77	A12	97	A3
18	J1	38	L7	58	J13	78	B11	98	A2
19	J2	39	N7	59	H11	79	A11	99	B3
20	K1	40	N8	60	H12	80	B10	100	A1

S/R	NC
D/A	NC
C3 EXTRA PIN	NC

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					101 PIN GRID ARRAY PACKAGE	±	K. IM	A.F./K.M	T.A	SEP.01.'93
					SCALE	MATERIAL				
					CHANGED	DATE	DRAWN	CHECKED	APPROVED	
						KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO.		SHEET
							KD-P93926		3/3	

